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"[Embedded - Microcontrollers](#)" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "[Embedded - Microcontrollers](#)"

Details

Product Status	Obsolete
Core Processor	ST7
Core Size	8-Bit
Speed	8MHz
Connectivity	I ² C, SCI, SPI
Peripherals	LVD, POR, PWM, WDT
Number of I/O	48
Program Memory Size	48KB (48K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	1.5K x 8
Voltage - Supply (Vcc/Vdd)	3.8V ~ 5.5V
Data Converters	A/D 16x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	64-LQFP
Supplier Device Package	-
Purchase URL	https://www.e-xfl.com/product-detail/stmicroelectronics/st72f321bar7tae

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Obsolete Product(s) - Obsolete Product(s)

1 Description

The ST72321Bxxx-Auto Flash and ROM devices are members of the ST7 microcontroller family designed for mid-range automotive applications running from 3.8 to 5.5 V.

All devices are based on a common industry-standard 8-bit core, featuring an enhanced instruction set and are available with Flash or ROM program memory. The ST7 family architecture offers both power and flexibility to software developers, enabling the design of highly efficient and compact application code.

The on-chip peripherals include an A/D converter, a PWM autoreload timer, two general purpose timers, I²C, SPI, and SCI interfaces.

For power economy, the microcontroller can switch dynamically into Wait, Slow, Active Halt or Halt mode when the application is in idle or standby state.

Typical applications include all types of car body applications such as window lift, DC motor control, rain sensors, car body controllers, low end junction boxes and auxiliary functions in car radios.

Related documentation

Migrating applications from ST72511/311/314 to ST72521/321/324 (AN1131)

2 Package pinout and pin description

2.1 Package pinout

Figure 2. 64-pin LQFP 14x14 and 10x10 package pinout

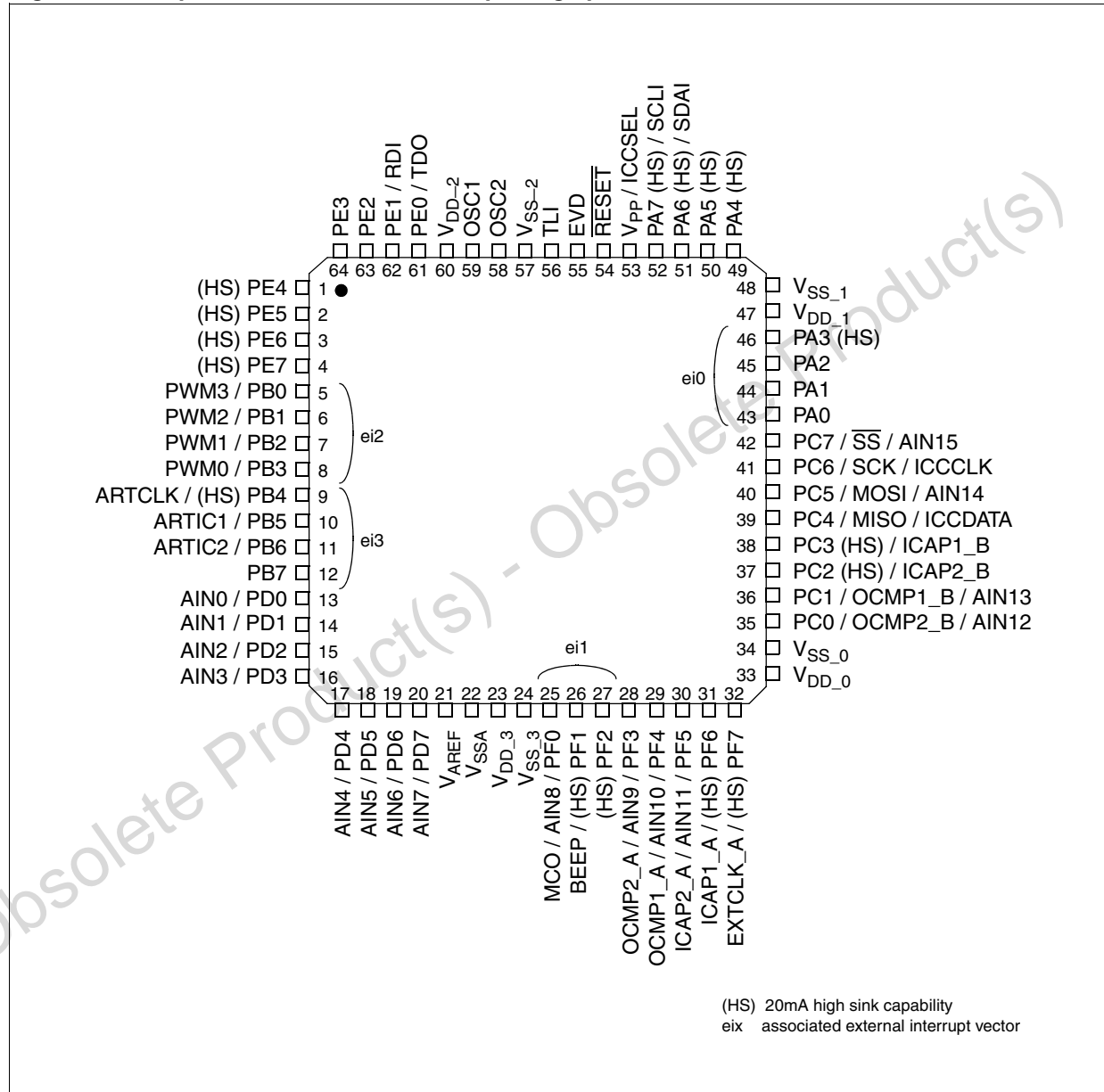
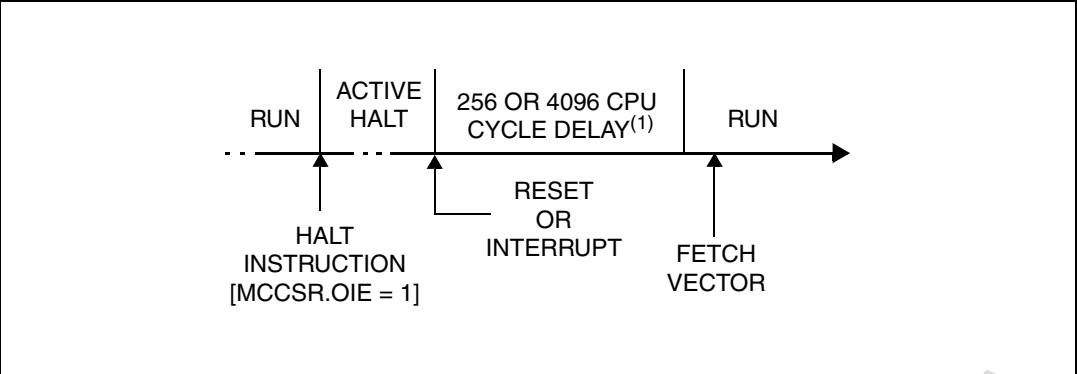
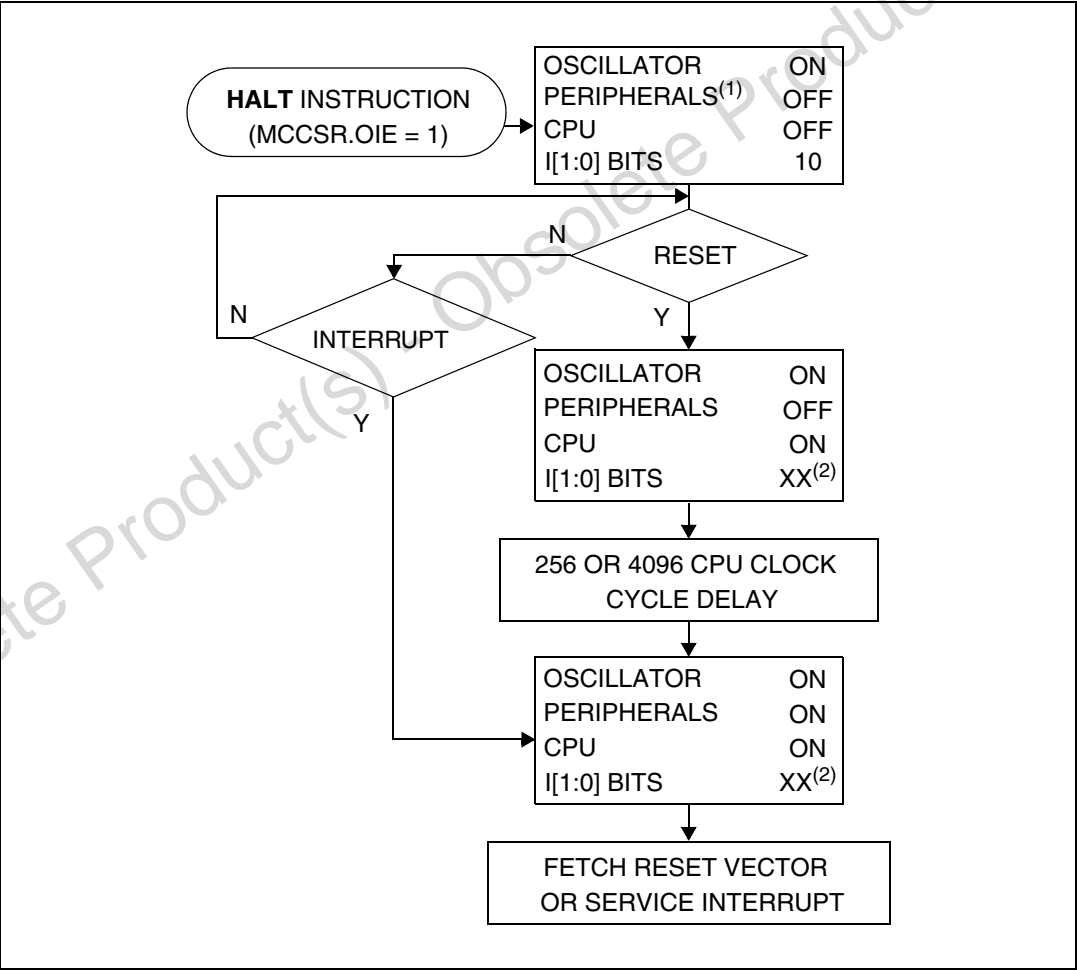


Figure 25. Active Halt timing overview



1. This delay occurs only if the MCU exits Active Halt mode by means of a RESET.

Figure 26. Active Halt mode flowchart



- 1. Peripheral clocked with an external clock source can still be active.
- 2. Before servicing an interrupt, the CC register is pushed on the stack. The I[1:0] bits of the CC register are set to the current software priority level of the interrupt routine and restored when the CC register is popped.

Figure 29. I/O port general block diagram

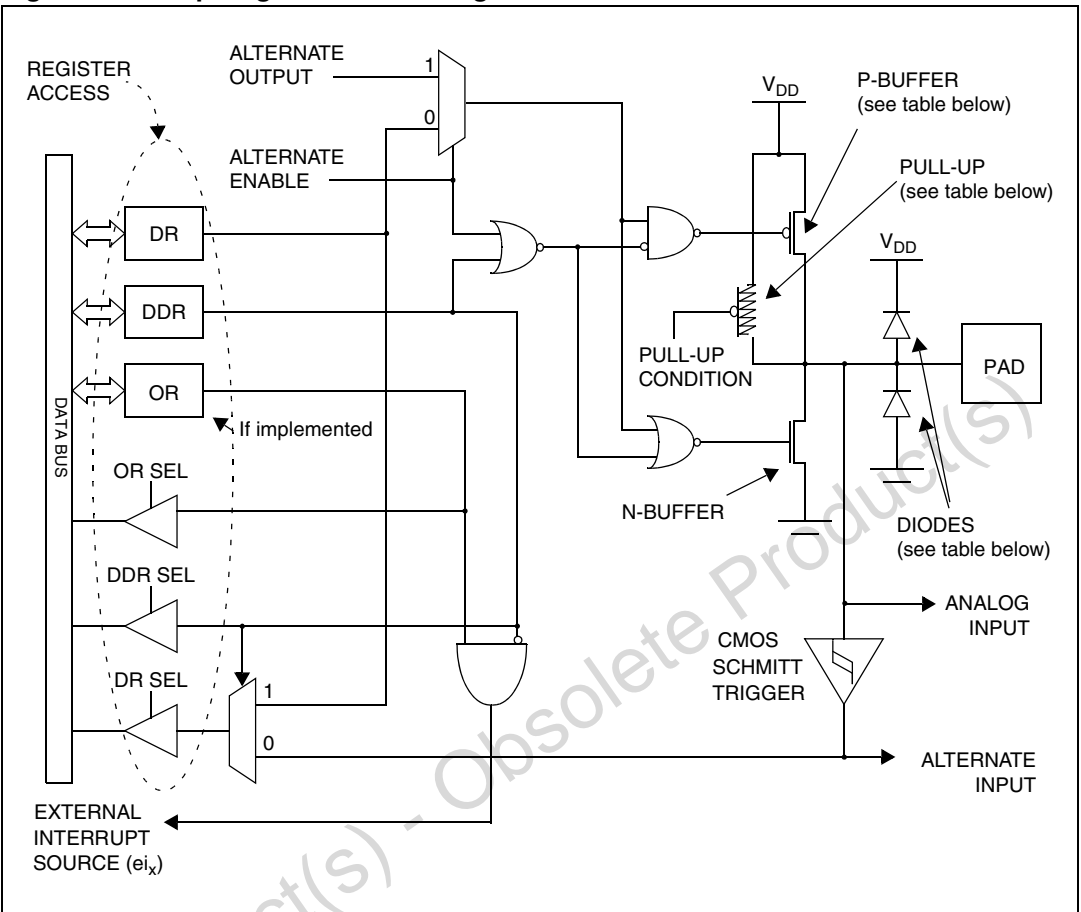


Table 28. I/O port mode options

Configuration mode		Pull-up	P-buffer	Diodes	
				to V _{DD}	to V _{SS}
Input	Floating with/without Interrupt	Off	Off	On	On
	Pull-up with/without Interrupt	On			
Output	Push-pull	Off	On		
	Open-drain (logic level)		Off		
	True open-drain	NI	NI	NI ⁽¹⁾	

1. The diode to V_{DD} is not implemented in the true open-drain pads. A local protection between the pad and V_{SS} is implemented to protect the device against positive stress.

Legend:

- Off - Implemented not activated
- On - Implemented and activated
- NI - Not implemented

10.5 Low power modes

Table 34. Effect of low power modes on WDG

Mode	Effect		
Slow	No effect on Watchdog		
Wait	No effect on Watchdog		
Halt	OIE bit in MCCR register	WDGHALT bit in Option Byte	
	0	0	No Watchdog reset is generated. The MCU enters Halt mode. The Watchdog counter is decremented once and then stops counting and is no longer able to generate a watchdog reset until the MCU receives an external interrupt or a reset. If an external interrupt is received, the Watchdog restarts counting after 256 or 4096 CPU clocks. If a reset is generated, the Watchdog is disabled (reset state) unless Hardware Watchdog is selected by option byte. For application recommendations see Section 10.7 below.
	0	1	A reset is generated.
	1	x	No reset is generated. The MCU enters Active Halt mode. The Watchdog counter is not decremented. It stop counting. When the MCU receives an oscillator interrupt or external interrupt, the Watchdog restarts counting immediately. When the MCU receives a reset the Watchdog restarts counting after 256 or 4096 CPU clocks.

10.6 Hardware watchdog option

If Hardware Watchdog is selected by option byte, the watchdog is always active and the WDGA bit in the WDGCR is not used. Refer to the option byte description in [Section 21.1.1: Flash configuration on page 225](#).

10.7 Using Halt mode with the WDG (WDGHALT option)

The following recommendation applies if Halt mode is used when the watchdog is enabled: Before executing the HALT instruction, refresh the WDG counter to avoid an unexpected WDG reset immediately after waking up the microcontroller.

10.8 Interrupts

None.

Table 39. MCCR register description (continued)

Bit	Name	Function
0	OIF	<p><i>Oscillator interrupt flag</i></p> <p>This bit is set by hardware and cleared by software reading the MCCR register. It indicates when set that the main oscillator has reached the selected elapsed time (TB1:0).</p> <p>0: Timeout not reached 1: Timeout reached</p> <p>Caution: The BRES and BSET instructions must not be used on the MCCR register to avoid unintentionally clearing the OIF bit.</p>

Table 40. Time base selection

Counter prescaler	Time base		TB1	TB0
	f _{OSC2} = 4 MHz	f _{OSC2} = 8 MHz		
16000	4ms	2ms	0	0
32000	8ms	4ms	0	1
80000	20ms	10ms	1	0
200000	50ms	25ms	1	1

11.8.2 MCC beep control register (MCCBCR)

MCCBCR

Reset value: 0000 0000 (00h)

7	6	5	4	3	2	1	0
Reserved						BC[1:0]	
						RW	

Table 41. MCCBCR register description

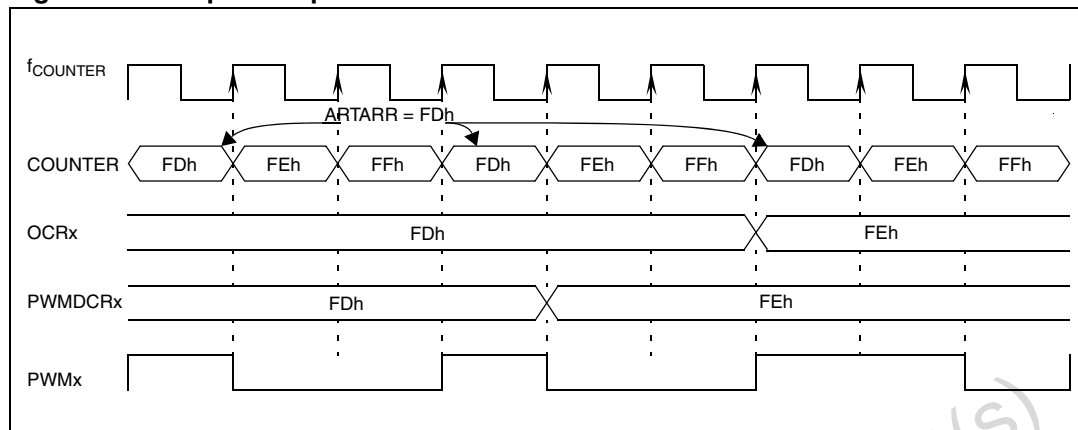
Bit	Name	Function
7:2	-	Reserved, must be kept cleared.
1:0	BC[1:0]	<p><i>Beep control</i></p> <p>These 2 bits select the PF1 pin beep capability (see Table 42).</p>

Table 42. Beep frequency selection

BC1	BC0	Beep mode with f _{OSC2} = 8 MHz	
0	0	Off	
0	1	~2 kHz	Output Beep signal ~50% duty cycle
1	0	~1 kHz	
1	1	~500 Hz	

The beep output signal is available in Active Halt mode but has to be disabled to reduce consumption.

Figure 36. Output compare control



12.2.5 Independent PWM signal generation

This mode allows up to four Pulse Width Modulated signals to be generated on the PWMx output pins with minimum core processing overhead. This function is stopped during Halt mode.

Each PWMx output signal can be selected independently using the corresponding OEx bit in the PWM Control register (PWMCR). When this bit is set, the corresponding I/O pin is configured as output push-pull alternate function.

The PWM signals all have the same frequency which is controlled by the counter period and the ARTARR register value.

$$f_{\text{PWM}} = f_{\text{COUNTER}} / (256 - \text{ARTARR})$$

When a counter overflow occurs, the PWMx pin level is changed depending on the corresponding OPx (output polarity) bit in the PWMCR register. When the counter reaches the value contained in one of the output compare register (OCRx) the corresponding PWMx pin level is restored.

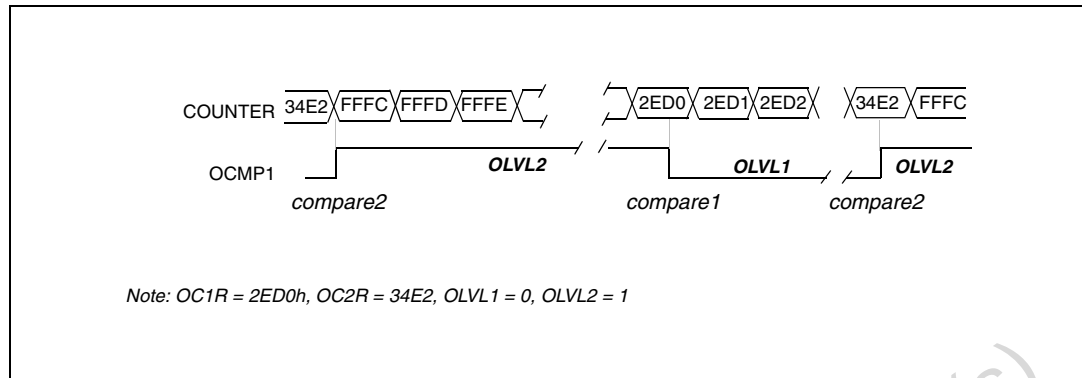
It should be noted that the reload values will also affect the value and the resolution of the duty cycle of the PWM output signal. To obtain a signal on a PWMx pin, the contents of the OCRx register must be greater than the contents of the ARTARR register.

The maximum available resolution for the PWMx duty cycle is:

$$\text{Resolution} = 1 / (256 - \text{ARTARR})$$

Note:

To get the maximum resolution (1/256), the ARTARR register must be 0. With this maximum resolution, 0% and 100% can be obtained by changing the polarity.

Figure 53. Pulse width modulation mode timing example with 2 output compare functions

Note: On timers with only one Output Compare register, a fixed frequency PWM signal can be generated using the output compare and the counter overflow to define the pulse length.

13.3.7 Pulse width modulation mode

Pulse Width Modulation (PWM) mode enables the generation of a signal with a frequency and pulse length determined by the value of the OC1R and OC2R registers.

Pulse Width Modulation mode uses the complete Output Compare 1 function plus the OC2R register, and so this functionality cannot be used when PWM mode is activated.

In PWM mode, double buffering is implemented on the output compare registers. Any new values written in the OC1R and OC2R registers are taken into account only at the end of the PWM period (OC2) to avoid spikes on the PWM output pin (OCMP1).

Procedure

To use pulse width modulation mode:

1. Load the OC2R register with the value corresponding to the period of the signal using the appropriate formula below according to the timer clock source used.
2. Load the OC1R register with the value corresponding to the period of the pulse if OLVL1 = 0 and OLVL2 = 1 using the appropriate formula below according to the timer clock source used.
3. Select the following in the CR1 register:
 - Using the OLVL1 bit, select the level to be applied to the OCMP1 pin after a successful comparison with the OC1R register.
 - Using the OLVL2 bit, select the level to be applied to the OCMP1 pin after a successful comparison with the OC2R register.
4. Select the following in the CR2 register:
 - Set OC1E bit: the OCMP1 pin is then dedicated to the output compare 1 function.
 - Set the PWM bit.
 - Select the timer clock (CC[1:0]) (see [Table 60: Timer clock selection](#)).

14.6 Low power modes

Table 63. Effect of low power modes on SPI

Mode	Effect
Wait	No effect on SPI. SPI interrupt events cause the device to exit from Wait mode.
Halt	SPI registers are frozen. In Halt mode, the SPI is inactive. SPI operation resumes when the MCU is woken up by an interrupt with “exit from Halt mode” capability. The data received is subsequently read from the SPIDR register when the software is running (interrupt vector fetching). If several data are received before the wake-up event, then an overrun error is generated. This error can be detected after the fetch of the interrupt routine that woke up the device.

14.6.1 Using the SPI to wake up the MCU from Halt mode

In slave configuration, the SPI is able to wake up the ST7 device from Halt mode through a SPIF interrupt. The data received is subsequently read from the SPIDR register when the software is running (interrupt vector fetch). If multiple data transfers have been performed before software clears the SPIF bit, then the OVR bit is set by hardware.

Note: When waking up from Halt mode, if the SPI remains in Slave mode, it is recommended to perform an extra communications cycle to bring the SPI from Halt mode state to normal state. If the SPI exits from Slave mode, it returns to normal state immediately.

Caution: The SPI can wake up the ST7 from Halt mode only if the Slave Select signal (external \overline{SS} pin or the SSI bit in the SPICSR register) is low when the ST7 enters Halt mode. So if Slave selection is configured as external (see [Slave select management on page 124](#)), make sure the master drives a low level on the \overline{SS} pin when the slave enters Halt mode.

14.7 Interrupts

Table 64. SPI interrupt control/wake-up capability

Interrupt event	Event flag	Enable control bit	Exit from Wait	Exit from Halt
SPI End of Transfer event	SPIF	SPIE	Yes	Yes
Master Mode Fault event	MODF			No
Overrun error	OVR			

Note: The SPI interrupt events are connected to the same interrupt vector (see *Interrupts chapter*). They generate an interrupt if the corresponding Enable Control Bit is set and the interrupt mask in the CC register is reset (RIM instruction).

16.3 General description

In addition to receiving and transmitting data, this interface converts it from serial to parallel format and vice versa, using either an interrupt or polled handshake. The interrupts are enabled or disabled by software. The interface is connected to the I²C bus by a data pin (SDA) and by a clock pin (SCL). It can be connected both with a standard I²C bus and a fast I²C bus. This selection is made by software.

16.3.1 Mode selection

The interface can operate in the four following modes:

- Slave transmitter/receiver
- Master transmitter/receiver

By default, it operates in slave mode.

The interface automatically switches from slave to master after it generates a START condition and from master to slave in case of arbitration loss or a STOP generation, allowing then Multimaster capability.

16.3.2 Communication flow

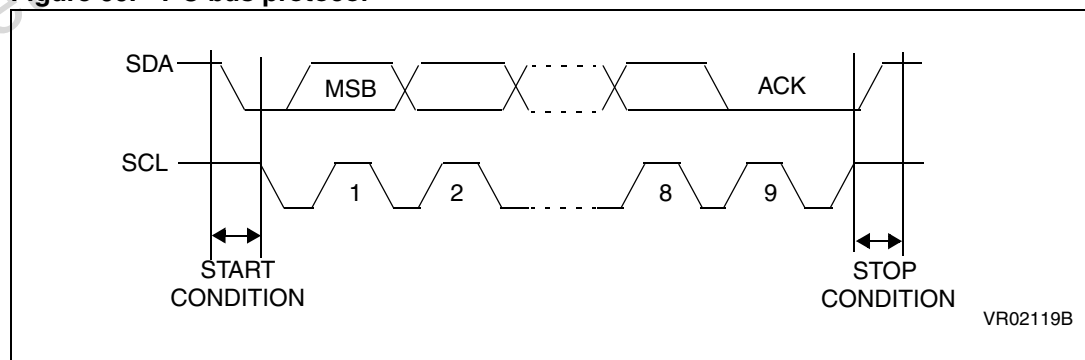
In Master mode, it initiates a data transfer and generates the clock signal. A serial data transfer always begins with a start condition and ends with a stop condition. Both start and stop conditions are generated in master mode by software.

In Slave mode, the interface is capable of recognizing its own address (7- or 10-bit), and the General Call address. The General Call address detection may be enabled or disabled by software.

Data and addresses are transferred as 8-bit bytes, MSB first. The first byte(s) following the start condition contain the address (one in 7-bit mode, two in 10-bit mode). The address is always transmitted in Master mode.

A 9th clock pulse follows the 8 clock cycles of a byte transfer, during which the receiver must send an acknowledge bit to the transmitter. Refer to [Figure 66](#).

Figure 66. I²C bus protocol



Acknowledge may be enabled and disabled by software.

The I²C interface address and/or general call address can be selected by software.

The speed of the I²C interface may be selected between standard (up to 100 kHz) and fast I²C (up to 400 kHz).

Table 83. SR1 register description (continued)

Bit	Name	Function
6	ADD10	<p><i>10-bit addressing in Master mode</i></p> <p>This bit is set by hardware when the master has sent the first byte in 10-bit address mode. It is cleared by software reading SR2 register followed by a write in the DR register of the second address byte. It is also cleared by hardware when the peripheral is disabled (PE = 0). 0: No ADD10 event occurred. 1: Master has sent first address byte (header)</p>
5	TRA	<p><i>Transmitter/Receiver</i></p> <p>When BTF is set, TRA = 1 if a data byte has been transmitted. It is cleared automatically when BTF is cleared. It is also cleared by hardware after detection of Stop condition (STOPF = 1), loss of bus arbitration (ARLO = 1) or when the interface is disabled (PE = 0). 0: Data byte received (if BTF = 1) 1: Data byte transmitted</p>
4	BUSY	<p><i>Bus busy</i></p> <p>This bit is set by hardware on detection of a Start condition and cleared by hardware on detection of a Stop condition. It indicates a communication in progress on the bus. The BUSY flag of the I2CSR1 register is cleared if a Bus Error occurs. 0: No communication on the bus 1: Communication ongoing on the bus</p> <p><i>Note: The BUSY flag is NOT updated when the interface is disabled (PE = 0). This can have consequences when operating in Multimaster mode; that is, a second active I²C master commencing a transfer with an unset BUSY bit can cause a conflict resulting in lost data. A software workaround consists of checking that the I²C is not busy before enabling the I²C Multimaster cell.</i></p>
3	BTF	<p><i>Byte transfer finished</i></p> <p>This bit is set by hardware as soon as a byte is correctly received or transmitted with interrupt generation if ITE = 1. It is cleared by software reading SR1 register followed by a read or write of DR register. It is also cleared by hardware when the interface is disabled (PE = 0). Following a byte transmission, this bit is set after reception of the acknowledge clock pulse. In case an address byte is sent, this bit is set only after the EV6 event (see Figure 68). BTF is cleared by reading SR1 register followed by writing the next byte in DR register. Following a byte reception, this bit is set after transmission of the acknowledge clock pulse if ACK = 1. BTF is cleared by reading SR1 register followed by reading the byte from DR register. The SCL line is held low while BTF = 1. 0: Byte transfer not done 1: Byte transfer succeeded</p>
2	ADSL	<p><i>Address matched (Slave mode)</i></p> <p>This bit is set by hardware as soon as the received slave address matched with the OAR register content or a general call is recognized. An interrupt is generated if ITE = 1. It is cleared by software reading SR1 register or by hardware when the interface is disabled (PE = 0). The SCL line is held low while ADSL = 1. 0: Address mismatched or not received 1: Received address matched</p>

Table 87. OAR1 register description

Bit	Name	Function	
		7-bit addressing mode	10-bit addressing mode
7:1	ADD[7:1]	<i>Interface address</i> These bits define the I ² C bus address of the interface. They are not cleared when the interface is disabled (PE = 0).	Not applicable
0	ADD0	<i>Address direction bit</i> This bit is 'don't care', the interface acknowledges either 0 or 1. It is not cleared when the interface is disabled (PE = 0). Address 01h is always ignored.	
7:0	ADD[7:0]	Not applicable	<i>Interface address</i> These are the least significant bits of the I ² C bus address of the interface. They are not cleared when the interface is disabled (PE = 0).

16.7.7 I²C own address register (OAR2)

OAR2

Reset value: 0100 0000 (40h)

7	6	5	4	3	2	1	0
FR[1:0]		Reserved			ADD[9:8]		Reserved
RW		-			RW		-

Table 88. OAR2 register description

Bit	Name	Function
7:6	FR[1:0]	<i>Frequency bits</i> These bits are set by software only when the interface is disabled (PE = 0). To configure the interface to I ² C specified delays, select the value corresponding to the CPU frequency f_{CPU} . 00: $f_{CPU} < 6$ MHz 01: $f_{CPU} = 6$ to 8 MHz
5:3	-	Reserved
2:1	ADD[9:8]	<i>Interface address</i> These are the most significant bits of the I ² C bus address of the interface (10-bit mode only). They are not cleared when the interface is disabled (PE = 0).
0	-	Reserved

19 Electrical characteristics

19.1 Parameter conditions

Unless otherwise specified, all voltages are referred to V_{SS} .

19.1.1 Minimum and maximum values

Unless otherwise specified the minimum and maximum values are guaranteed in the worst conditions of ambient temperature, supply voltage and frequencies by tests in production on 100% of the devices with an ambient temperature at $T_A = 25^\circ\text{C}$ and $T_A = T_{Amax}$ (given by the selected temperature range).

Data based on characterization results, design simulation and/or technology characteristics are indicated in the table footnotes and are not tested in production. Based on characterization, the minimum and maximum values refer to sample tests and represent the mean value plus or minus three times the standard deviation (mean $\pm 3\sigma$).

19.1.2 Typical values

Unless otherwise specified, typical data is based on $T_A = 25^\circ\text{C}$, $V_{DD} = 5\text{V}$. The typical values are given only as design guidelines and are not tested.

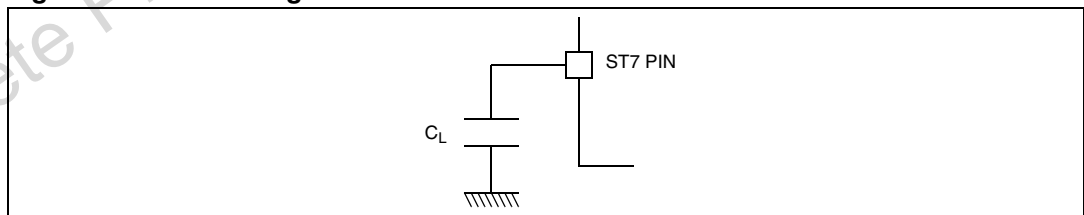
19.1.3 Typical curves

Unless otherwise specified, all typical curves are given only as design guidelines and are not tested.

19.1.4 Loading capacitor

The loading conditions used for pin parameter measurement are shown in [Figure 71](#).

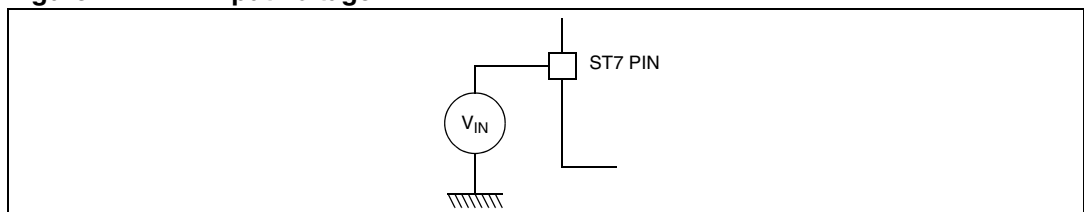
Figure 71. Pin loading conditions



19.1.5 Pin input voltage

The input voltage measurement on a pin of the device is described in [Figure 72](#).

Figure 72. Pin input voltage



19.4.3 On-chip peripherals

Measured on LQFP64 generic board $T_A = 25^\circ\text{C}$, $f_{\text{CPU}} = 4 \text{ MHz}$.

Table 112. On-chip peripherals current consumption

Symbol	Parameter	Conditions	Typ	Unit
$I_{\text{DD(TIM)}}$	16-bit timer supply current ⁽¹⁾	$V_{\text{DD}} = 5.0\text{V}$	50	μA
$I_{\text{DD(ART)}}$	ART PWM supply current ⁽²⁾	$V_{\text{DD}} = 5.0\text{V}$	75	μA
$I_{\text{DD(SPI)}}$	SPI supply current ⁽³⁾	$V_{\text{DD}} = 5.0\text{V}$	400	μA
$I_{\text{DD(SCI)}}$	SCI supply current ⁽⁴⁾			
$I_{\text{DD(I2C)}}$	I2C supply current ⁽⁵⁾	$V_{\text{DD}} = 5.0\text{V}$	175	μA
$I_{\text{DD(ADC)}}$	ADC supply current when converting ⁽⁶⁾	$V_{\text{DD}} = 5.0\text{V}$	400	μA

1. Data based on a differential I_{DD} measurement between reset configuration (timer counter running at $f_{\text{CPU}}/4$) and timer counter stopped (only TIMD bit set). Data valid for one timer.
2. Data based on a differential I_{DD} measurement between reset configuration (timer stopped) and timer counter enabled (only TCE bit set).
3. Data based on a differential I_{DD} measurement between reset configuration (SPI disabled) and a permanent SPI master communication at maximum speed (data sent equal to 55h). This measurement includes the pad toggling consumption.
4. Data based on a differential I_{DD} measurement between SCI low power state (SCID = 1) and a permanent SCI data transmit sequence.
5. Data based on a differential I_{DD} measurement between reset configuration (I2C disabled) and a permanent I2C master communication at 100 kHz (data sent equal to 55h). This measurement includes the pad toggling consumption (27k ohm external pull-up on clock and data lines).
6. Data based on a differential I_{DD} measurement between reset configuration and continuous A/D conversions.

19.7 EMC (electromagnetic compatibility) characteristics

Susceptibility tests are performed on a sample basis during product characterization.

19.7.1 Functional EMS (electromagnetic susceptibility)

Based on a simple running application on the product (toggling two LEDs through I/O ports), the product is stressed by two electromagnetic events until a failure occurs (indicated by the LEDs).

- **ESD:** Electrostatic discharge (positive and negative) is applied on all pins of the device until a functional disturbance occurs. This test conforms with the IEC 1000-4-2 standard.
- **FTB:** A burst of fast transient voltage (positive and negative) is applied to V_{DD} and V_{SS} through a 100pF capacitor until a functional disturbance occurs. This test conforms with the IEC 1000-4-4 standard.

A device reset allows normal operations to be resumed. The test results given in [Table 121](#) below are based on the EMS levels and classes defined in application note AN1709.

Designing hardened software to avoid noise problems

EMC characterization and optimization are performed at component level with a typical application environment and simplified MCU software. It should be noted that good EMC performance is highly dependent on the user application and the software in particular.

Therefore it is recommended that the user applies EMC software optimization and prequalification tests in relation with the EMC level requested for his application.

Software recommendations

The software flowchart must include the management of runaway conditions such as:

- Corrupted program counter
- Unexpected reset
- Critical Data corruption (control registers...)

Prequalification trials

Most of the common failures (unexpected reset and program counter corruption) can be reproduced by manually forcing a low state on the \overline{RESET} pin or the oscillator pins for 1 second.

To complete these trials, ESD stress can be applied directly on the device, over the range of specification values. When unexpected behavior is detected, the software can be hardened to prevent unrecoverable errors occurring (see application note AN1015).

19.11.2 I²C - inter IC control interface

Subject to general operating conditions for V_{DD} , f_{CPU} , and T_A unless otherwise specified.

Refer to [Section 19.8: I/O port pin characteristics](#) for more details on the input/output alternate function characteristics (SDAI and SCLI). The ST7 I2C interface meets the requirements of the standard I2C communication protocol described in the following table.

Table 132. I²C control interface characteristics

Symbol	Parameter	Standard mode I ² C		Fast mode I ² C ⁽¹⁾		Unit
		Min ⁽²⁾	Max ⁽²⁾	Min ⁽²⁾	Max ⁽²⁾	
t _w (SCLL)	SCL clock low time	4.7		1.3		μs
t _w (SCLH)	SCL clock high time	4.0		0.6		
t _{su} (SDA)	SDA setup time	250		100		ns
t _h (SDA)	SDA data hold time	0 ⁽³⁾		0 ⁽⁴⁾	900 ⁽³⁾	
t _r (SDA) t _r (SCL)	SDA and SCL rise time		1000	20+0.1C _b	300	
t _f (SDA) t _f (SCL)	SDA and SCL fall time		300			
t _h (STA)	START condition hold time	4.0		0.6		μs
t _{su} (STA)	Repeated START condition setup time	4.7				
t _{su} (STO)	STOP condition setup time	4.0				
t _w (STO:STA)	STOP to START condition time (bus free)	4.7		1.3		
C _b	Capacitive load for each bus line		400		400	pF

- At 4 MHz f_{CPU} , maximum I²C speed (400 kHz) is not achievable. In this case, maximum I²C speed will be approximately 260 kHz.
- Data based on standard I²C protocol requirement, not tested in production.
- The maximum hold time of the START condition has only to be met if the interface does not stretch the low period of SCL signal.
- The device must internally provide a hold time of at least 300ns for the SDA signal in order to bridge the undefined region of the falling edge of SCL.

20 Package characteristics

Figure 99. 64-pin (14x14) low profile quad flat package outline

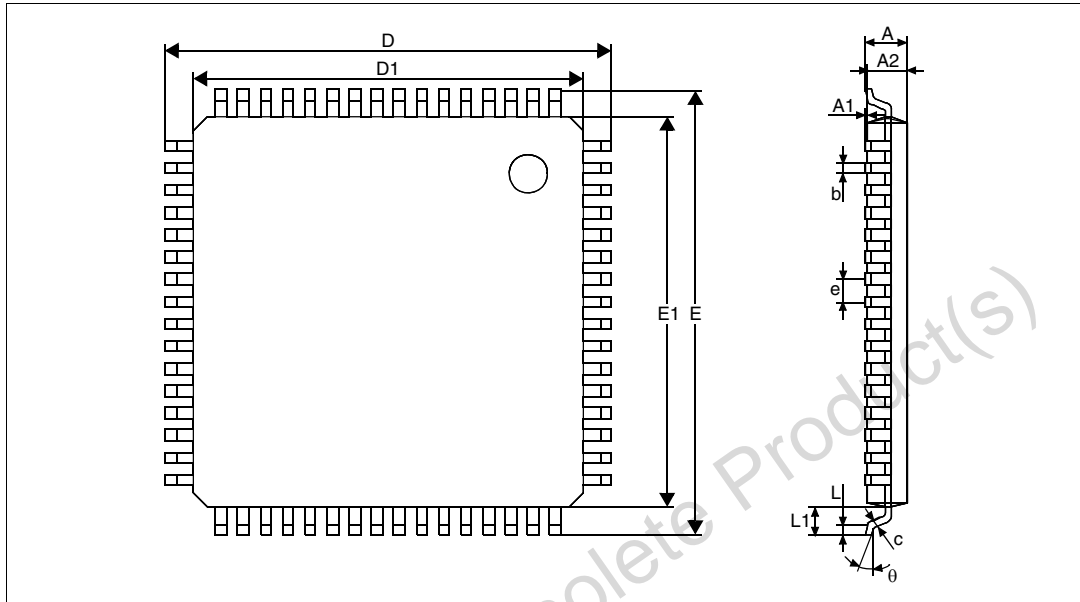


Table 136. 64-pin (14x14) low profile quad flat package mechanical data

Dimension	mm			inches ⁽¹⁾		
	Min	Typ	Max	Min	Typ	Max
A			1.600			0.0630
A1	0.050		0.150	0.0020		0.0059
A2	1.350	1.400	1.450	0.0531	0.0551	0.0571
b	0.300	0.370	0.450	0.0118	0.0146	0.0177
c	0.090		0.200	0.0035		0.0079
D		16.000			0.6299	
D1		14.000			0.5512	
E		16.000			0.6299	
E1		14.000			0.5512	
e		0.800			0.0315	
θ	0°	3.5°	7°	0°	3.5°	7°
L	0.450	0.600	0.750	0.0177	0.0236	0.0295
L1		1.000			0.0394	

1. Values in inches are converted from mm and rounded to 4 decimal digits.